

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S21 2	4569112	back backside bottom underneath underbody undersurface underside second! adj side	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 18:14
S21 3	444993	epoxy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 18:14
S21 4	1995132	resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 18:14
S21 5	1956794	polymer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 18:14
S21 6	116852	glue	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 18:14
S21 7	3570083	layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 18:15
S21 8	172916	S212 near2 (S213 S214 S215 S216 S217)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 18:15
S21 9	44836	(scrib\$4 guide border) near2 (line grid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 18:32
S22 0	2985226	dicing dice saw\$4 cutting cut laser ablat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 18:19

EAST Search History

S22 1	7790	S219 same S220	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 18:33
S22 2	670	S221 and S218	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 18:19
S22 3	462	S222 and (@ad < "20021122")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 18:34
S22 4	160724	(scrib\$4 guide border) near2 (line grid groove channel)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 18:33
S22 5	44836	S219 same S224	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 18:33
S22 6	1086	S225 and S218 and (@ad < "20021122")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 18:41
S22 7	2698210	ic integrated adj circuit semiconductor silicon	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 18:42
S22 8	698	S226 and S227	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 18:42
S22 9	2	"20040161908".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 17:56
S23 0	3003715	heat	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 17:56

EAST Search History

S23 1	1	S229 and S230	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 18:00
S23 2	1	S229 and S230 near2 conduct\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 18:01
S23 3	447435	epoxy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 13:43
S23 4	2005091	resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 13:41
S23 5	4556643	back backside bottom underneath underbody undersurface underside	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 13:41
S23 6	11591	scrib\$4 near (lines mark\$4 guide feature channel trench groove)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 13:41
S23 7	56	S235 same (S233 S234 (heat thermal) near2 (layer spread)) same S236	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 13:53
S23 8	1609026	selectiv\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 13:43
S23 9	75	S238 near4 (S233 S234 (heat thermal)) and S236	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 13:44
S24 0	56	S239 and (@ad < "20021122")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 13:53

EAST Search History

S24 1	1297	S235 same (S233 S234 (heat thermal)) and S236	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 13:52
S24 2	137	S235 same (S233 S234 (heat thermal)) same S236	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 13:52
S24 3	663	S235 same (S233 S234 (heat thermal) near2 (layer spread)) and S236	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 14:13
S24 4	409	S243 and (@ad < "20021122")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 14:13
S24 5	9	(S235 same (S233 S234 (heat thermal) near2 (layer spread)) and S236).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 14:14
S24 6	57223	scrib\$4 dicing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 14:15
S24 7	447435	epoxy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 14:15
S24 8	2005091	resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 14:15
S24 9	4556643	back backside bottom underneath underbody undersurface underside	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 14:15
S25 0	84282	S249 with (S247 S248)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 14:15

EAST Search History

S25 1	32842	scrib\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 14:15
S25 2	35543	dicing singulat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 14:15
S25 3	2	(S250 and S246 and S251 and S252). clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 14:21
S25 4	3074	((438/113) or (438/114) or (438/126) or (438/127)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/24 14:25